ROHM SEMICONDUCTOR

Under Development

Mid Voltage Series
MOSFET Nch 6th Gen & Pch 5th Gen
Product line-up and Cu-Clip Packaging Technology

GENERAL DESCRIPTION

MOSFET series that incorporates a new process die that contributes to improve efficiency. Combining next gen fab process with new Cu-Clip packaging, allows significantly lower RDSon and higher current capability. Convert existing bigger TO252 and TO220 solutions to smaller 5x6mm and 3.3x3.3mm packages.

FEATURES

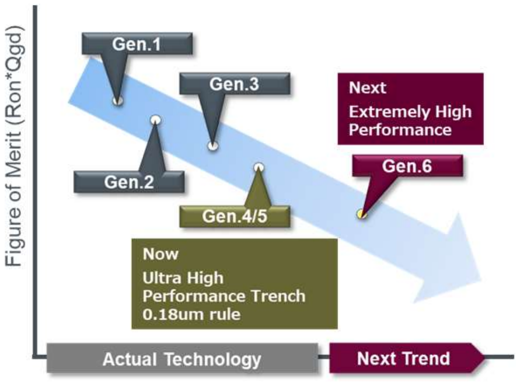
- Higher efficiency
- High Current Rating
- Improved Thermal Radiation
- Reduce Conduction losses

APPLICATIONS

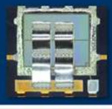
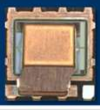
- **Industrial**: Motors, Data Center Servers, Base Station/Telecom, Power Supplies, PLC
- **Consumer**: Vacuum Cleaners, Power tools, Charge Stations
- **Automotive**: ECU, EPS, Inverters, Motors
- All 12V/24V/48V Systems

ADVANTAGE

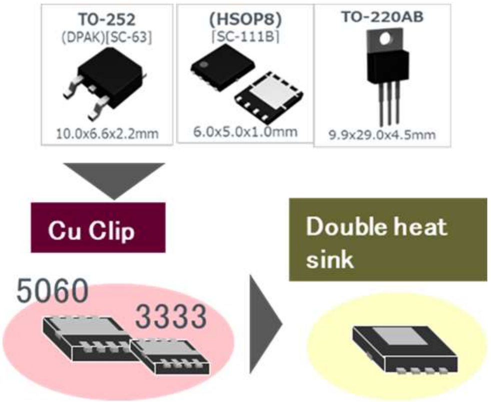
Higher efficiency



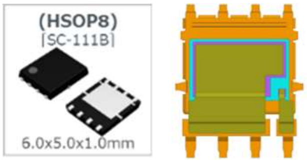
Higher Current Rating

5060 PKG	HSOP8 (Al Ribon) 	5060 PKG(Cu Clip) 
Max Id	≦80A	**≦120A**
Package Ron	0.6mΩ	**0.2mΩ**

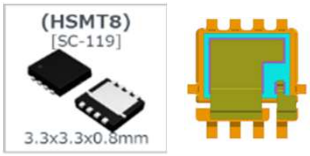
Allows Package Downsizing



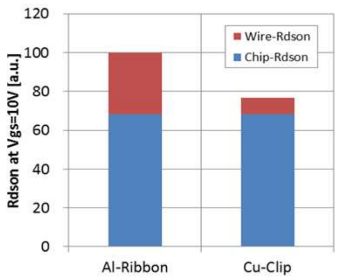
PACKAGE (Cu-Clip)



HSOP8(5060)Cu Clip



HSMT8(3333) Cu Clip



Reduce package resistance

LINE-UP

Packages	40V	60V	100V	150V	-40V	-60V
DFN2020-8S	✔	✔	✔		✔	✔
TSMT8M (3028)	✔	✔			✔	✔
HSMT8 (3333)	✔	✔	✔	✔		
HSOP8 (5060)	✔	✔	✔	✔	✔	✔
TO252	✔	✔	✔	✔	✔	✔
TO263			✔	✔		
TO220	✔	✔	✔	✔		